01 July 2003



L Number	Hits	S arch Text	DB	Time stamp
1	4	216/58,83.ccls. and (diffraction adj (grate or grating))	USPAT; US-PGPUB;	2003/06/30 10:34
		, , , , , , , , , , , , , , , , , , ,	EPO; JPO; DERWENT	
	163	216 /t - le and (differentian adi (anata an anatina))	USPAT;	2003/06/30
2	103	216/\$.ccls. and (diffraction adj (grate or grating))	US-PGPUB;	10:40
			EPO; JPO;	10.40
			DERWENT	
3	6	(216/\$.ccls. and (diffraction adj (grate or grating)))	USPAT;	2003/06/30
		and (solar or photovoltaic)	US-PGPUB;	10:38
			EPO; JPO;	
			DERWENT	
4	. 42	(216/\$.ccls. and (diffraction adj (grate or grating)))	USPAT;	2003/06/30
		and (reactive adj ion adj etch\$3)	US-PGPUB;	10:41
			EPO; JPO;	
	24	216/\$	DERWENT	2002/04/20
5	26	216/\$.ccls. and ((diffraction adj (grate or grating)) with (transmi\$7 or transparent))	USPAT; US-PGPUB;	2003/06/30 10:41
		with (iransmity) or iransparent))	EPO; JPO;	10.71
	•		DERWENT	·
6	7	(216/\$.ccls. and ((diffraction adj (grate or grating))	USPAT;	2003/06/30
-	·	with (transmi\$7 or transparent))) and (reactive adj	US-PGPUB;	11:25
		ion adj etch\$3)	EPO; JPO;	
			DERWENT	
7	343	136/\$.ccls. and (ion adj implantation)	USPAT;	2003/06/30
			US-PGPUB;	11:25
			EPO; JPO;	
8	41	(136/\$.ccls. and (ion adj implantation)) and	DERWENT USPAT;	2003/06/30
٥	, 71	(diffraction or diffractive)	US-PGPUB;	11:25
		(arriagnor arrivagnite)	EPO; JPO;	11.10
			DERWENT	
9	3	(136/\$.ccls. and (ion adj implantation)) and	USPAT;	2003/06/30
	•	((diffraction or diffractive) adj grating)	US-PGPUB;	12:03
		·	EPO; JPO;	
,,	27	197 /A L // // / /	DERWENT	2002/0//20
10	27	136/\$.ccls. and ((rie or (reactive adj ion adj etch\$3)) with (contamin\$7 or clean or remov\$3))	USPAT; US-PGPUB;	2003/06/30 12:08
		MILLI (COLLAMINA) OF CIERTI OF LEMONAS))	EPO; JPO;	12.00
			DERWENT	
	0	216/\$.ccls. and ((rie or (reactive adj ion adj etch\$3))	USPAT;	2003/06/30
		with (contamin\$7 or clean\$3))	US-PGPUB;	12:08
			EPO; JPO;	
			DERWENT	
13	27	136/\$.ccls. and ((rie or (reactive adj ion adj etch\$3))	USPAT;	2003/06/30
		with (contamin\$7 or clean\$3 or remov\$3))	US-PGPUB;	12:08
		•	EPO; JPO;	
	93	216/\$.ccls. and ((ri or (reactive adj ion adj etch\$3))	DERWENT. USPAT;	2003/06/30
	93	with (contamin\$7 or clean\$3))	US-PGPUB;	12:18
'		(comannity of disampon)	EPO; JPO;	1
		•	DERWENT	

14	76	(216/\$.ccls. and ((rie or (reactive adj ion adj	USPAT;	2003/06/30
		tch\$3)) with (contamin\$7 or clean\$3))) and silicon	US-PGPUB; EPO; JPO;	12:15
			DERWENT	·
15	17	(216/\$.ccls. and ((rie or (reactiv adj ion adj	USPAT;	2003/06/30
		etch\$3)) with (contamin\$7 or clean\$3))) not silicon	US-PGPUB;	12:16
			EPO; JPO;	,
		*	DERWENT	
16	76	(216/\$.ccls. and ((rie or (reactive adj ion adj	USPAT;	2003/06/30
		etch\$3)) with (contamin\$7 or clean\$3))) not	US-PGPUB;	12:16
		((216/\$.ccls. and ((rie or (reactive adj ion adj	EPO; JPO;	•
		etch\$3)) with (contamin\$7 or clean\$3))) not silicon)	DERWENT	
17	0	((216/\$.ccls. and ((rie or (reactive adj ion adj	USPAT;	2003/06/30
		etch\$3)) with (contamin\$7 or clean\$3))) not	US-PGPUB;	12:19
		((216/\$.ccls. and ((rie or (reactive adj ion adj	EPO; JPO;	
		etch\$3)) with (contamin\$7 or clean\$3))) not silicon))	DERWENT	
		and ((clean\$5 or contamin\$7) with ((potassium adj		
		hydroxide) or koh! or (wet adj chemical adj etch\$3)))		
18	180	216/\$.ccls. and ((rie or (reactive adj ion adj etch\$3))	USPAT;	2003/06/30
		with (contamin\$7 or clean\$3 or damag\$3))	US-PGPUB;	12:19
			EPO; JPO;	
40.			DERWENT	2000 101 100
19	33	(216/\$.ccls. and ((rie or (reactive adj ion adj	USPAT;	2003/06/30
		etch\$3)) with (contamin\$7 or clean\$3 or damag\$3)))	US-PGPUB;	12:19
		not silicon	EPO; JPO;	
20	147	(21/ 1/t 1 1 (/-) (/ 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	DERWENT	2002/07/20
20	147	(216/\$.ccls. and ((rie or (reactive adj ion adj	USPAT;	2003/06/30 12:19
		etch\$3)) with (contamin\$7 or clean\$3 or damag\$3)))	US-PGPUB;	12:19
		not ((216/\$.ccls. and ((rie or (reactive adj ion adj	EPO; JPO;	
		etch\$3)) with (contamin\$7 or clean\$3 or damag\$3))) not silicon)	DERWENT	
21	0	((216/\$.ccls. and ((rie or (reactive adj ion adj	USPAT;	2003/06/30
		etch\$3)) with (contamin\$7 or clean\$3 or damag\$3)))	US-PGPUB;	12:19
		not ((216/\$.ccls. and ((rie or (reactive adj ion adj	EPO; JPO;	
		etch\$3)) with (contamin\$7 or clean\$3 or damag\$3)))	DERWENT	
		not silicon)) and ((clean\$5 or contamin\$7) with		
		((potassium adj hydroxide) or koh! or (wet adj		
		chemical adj etch\$3)))		
22	2	((216/\$.ccls. and ((rie or (reactive adj ion adj	· USPAT;	2003/06/30
		etch\$3)) with (contamin\$7 or clean\$3 or damag\$3)))	US-PGPUB;	12:19
		not ((216/\$.ccls. and ((rie or (reactive adj ion adj	EPO; JPO;	
		etch\$3)) with (contamin\$7 or clean\$3 or damag\$3)))	DERWENT	
		not silicon)) and ((clean\$5 or contamin\$7 or	1	
		damag\$4) with ((potassium adj hydroxide) or koh! or		·
		(wet adj chemical adj etch\$3)))		